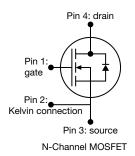


Vishay Siliconix

## **E Series Power MOSFET**





PRODUCT SUMMARY					
V <sub>DS</sub> (V) at T <sub>J</sub> max.	700				
R <sub>DS(on)</sub> typ. (Ω) at 25 °C	$V_{GS} = 10 \text{ V}$	0.106			
Q <sub>g</sub> max. (nC)	5	7			
Q <sub>gs</sub> (nC)	1	5			
Q <sub>gd</sub> (nC)	14				
Configuration	Sin	Single			

#### **FEATURES**

- 4<sup>th</sup> generation E series technology
- Low figure-of-merit (FOM) Ron x Qg
- Low effective capacitance (Co(er))
- · Reduced switching and conduction losses
- Avalanche energy rated (UIS)
- · Kelvin connection for reduced gate noise
- Material categorization: for definitions of compliance please see <a href="https://www.vishav.com/doc?99912"><u>www.vishav.com/doc?99912</u></a>



#### **APPLICATIONS**

- Server and telecom power supplies
- Switch mode power supplies (SMPS)
- Power factor correction power supplies (PFC)
- Lighting
  - High-intensity discharge (HID)
  - Fluorescent ballast lighting
- Industrial
  - Welding
  - Induction heating
  - Motor drives
  - Battery chargers
  - Solar (PV inverters)

ORDERING INFORMATION	
Package	PowerPAK 8 x 8
Lead (Pb)-free and halogen-free	SiHH125N65E-T1-GE3

ABSOLUTE MAXIMUM RATINGS	(T <sub>C</sub> = 25 °C, unless otherwi	se noted)		
PARAMETER	SYMBOL	LIMIT	UNIT	
Drain-source voltage	$V_{DS}$	650		
Gate-source voltage	$V_{GS}$	± 30	V	
Continuous drain current (T <sub>.I</sub> = 150 °C)	urrent (T <sub>J</sub> = 150 °C) $V_{GS} \text{ at } 10 \text{ V} \frac{T_C = 25 °C}{T_C = 100 °C}$		25	
Continuous drain current (1) = 150 °C)	$V_{GS}$ at 10 V $T_{C} = 100 ^{\circ}\text{C}$	ID	16	Α
Pulsed drain current <sup>a</sup>	I <sub>DM</sub>	60		
Linear derating factor			1.38	W/°C
Single pulse avalanche energy <sup>b</sup>		E <sub>AS</sub>	81	mJ
Maximum power dissipation		$P_D$	174	W
Operating junction and storage temperature ran	nge	T <sub>J</sub> , T <sub>stg</sub>	-55 to +150	°C
Drain-source voltage slope	dv/dt	100	V/ns	
Reverse diode dv/dt <sup>c</sup>		uv/ut	7.1	V/115

#### Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature
- b.  $V_{DD}$  = 140 V, starting  $T_J$  = 25 °C, L = 28.2 mH,  $R_q$  = 25  $\Omega$ ,  $I_{AS}$  = 2.4 A
- c.  $I_{SD} \le I_D$ , di/dt = 100 A/ $\mu$ s, starting  $T_J$  = 25 °C



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THERMAL RESISTANCE RATINGS						
PARAMETER SYMBOL TYP. MAX. UNIT						
Maximum junction-to-ambient	R <sub>thJA</sub>	40	42	°C/W		
Maximum junction-to-case (drain)	R <sub>thJC</sub>	0.55	0.72	C/ VV		

PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static							
Drain-source breakdown voltage	V <sub>DS</sub>	V <sub>GS</sub> =	= 0 V, I <sub>D</sub> = 250 μA	650	-	-	V
V <sub>DS</sub> temperature coefficient	$\Delta V_{DS}/T_{J}$	Referenc	e to 25 °C, I <sub>D</sub> = 1 mA	-	0.61	-	V/°C
Gate-source threshold voltage (N)	V <sub>GS(th)</sub>	V <sub>DS</sub> =	· V <sub>GS</sub> , I <sub>D</sub> = 250 μA	3.0	-	5.0	V
	I <sub>GSS</sub>	,	$V_{GS} = \pm 20 \text{ V}$		-	± 100	nA
Gate-source leakage		,	$V_{GS} = \pm 30 \text{ V}$	-	-	± 1	μΑ
Zana mata walta aa ahaa'a awaant		V <sub>DS</sub> =	650 V, V <sub>GS</sub> = 0 V	-	-	1	
Zero gate voltage drain current	I <sub>DSS</sub>	V <sub>DS</sub> = 520 V	, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 125 °C	-	-	10	μA
Drain-source on-state resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V	I <sub>D</sub> = 12 A	-	0.106	0.120	Ω
Forward transconductance <sup>a</sup>	9 <sub>fs</sub>	V <sub>DS</sub>	= 8 V, I <sub>D</sub> = 12 A	-	11	-	S
Dynamic		•		•		•	
Input capacitance	C <sub>iss</sub>		V <sub>GS</sub> = 0 V,	-	1938	-	
Output capacitance	C <sub>oss</sub>	╡ ,	$V_{DS} = 100 \text{ V},$	-	71	-	-
Reverse transfer capacitance	C <sub>rss</sub>	7	f = 100 kHz	-	2	-	
Effective output capacitance, energy related <sup>a</sup>	C <sub>o(er)</sub>	., .,	V <sub>DS</sub> = 0 V to 400 V, V <sub>GS</sub> = 0 V		81	-	pF
Effective output capacitance, time related <sup>b</sup>	$C_{o(tr)}$	$V_{DS} = 0$			546	-	
Total gate charge	Qg			-	38	57	
Gate-source charge	Q <sub>gs</sub>	$V_{GS} = 10 \text{ V}$ $I_D = 12 \text{ A}, V_{DS} = 520 \text{ V}$		-	15	-	nC
Gate-drain charge	Q <sub>gd</sub>			-	14	-	
Turn-on delay time	t <sub>d(on)</sub>	V <sub>DD</sub> = 520 V, I <sub>D</sub> = 12 A,		-	26	52	
Rise time	t <sub>r</sub>			-	59	118	
Turn-off delay time	t <sub>d(off)</sub>		$= 10 \text{ V}, \text{ R}_{\text{g}} = 9.1 \Omega$	-	46	92	ns
Fall time	t <sub>f</sub>	7			26	52	
Gate input resistance	R <sub>g</sub>	f = 1 MHz		0.4	0.8	1.6	Ω
<b>Drain-Source Body Diode Characteristic</b>	s						
Continuous source-drain diode current	I <sub>S</sub>	MOSFET symbol showing the integral reverse p - n junction diode		-	-	25	
Pulsed diode forward current	I <sub>SM</sub>			-	-	60	A
Diode forward voltage	V <sub>SD</sub>	T <sub>J</sub> = 25 °C, I <sub>S</sub> = 12 A, V <sub>GS</sub> = 0 V		-	-	1.2	V
Reverse recovery time	t <sub>rr</sub>	$T_J = 25 \text{ °C}, I_F = I_S = 12 \text{ A},$ $di/dt = 100 \text{ A/}\mu\text{s}, V_R = 25 \text{ V}$		-	345	690	ns
Reverse recovery charge	Q <sub>rr</sub>			-	4.4	8.8	μC
Reverse recovery current	I <sub>RRM</sub>			_	22	-	A



### TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

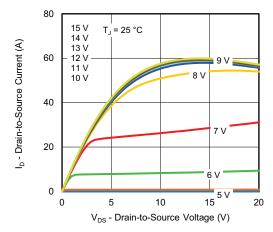


Fig. 1 - Typical Output Characteristics

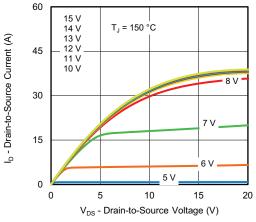


Fig. 2 - Typical Output Characteristics

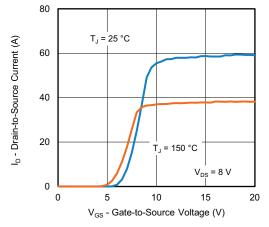


Fig. 3 - Typical Transfer Characteristics

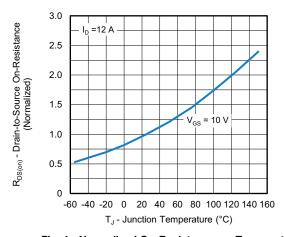


Fig. 4 - Normalized On-Resistance vs. Temperature

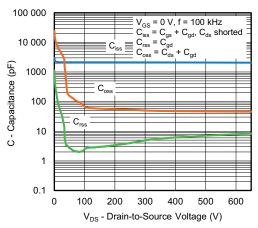


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

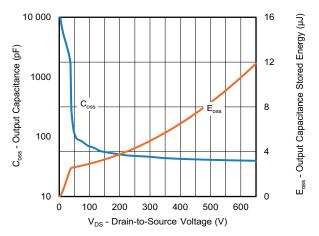


Fig. 6 - Coss and Eoss vs. VDS



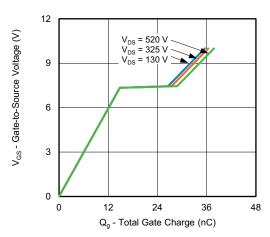


Fig. 7 - Typical Gate Charge vs. Gate-to-Source Voltage

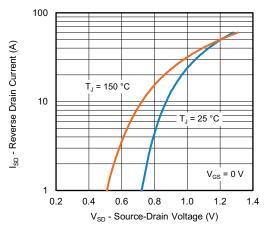


Fig. 8 - Typical Source-Drain Diode Forward Voltage

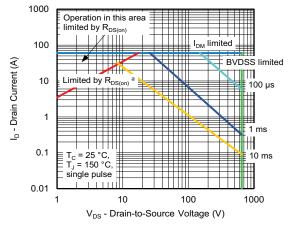


Fig. 9 - Maximum Safe Operating Area

#### Note

a. V<sub>GS</sub> > minimum V<sub>GS</sub> at which R<sub>DS(on)</sub> is specified

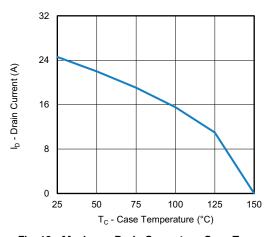


Fig. 10 - Maximum Drain Current vs. Case Temperature

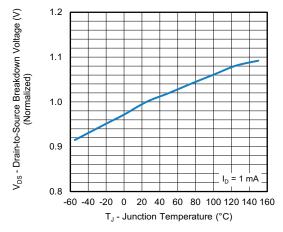


Fig. 11 - Temperature vs. Drain-to-Source Voltage



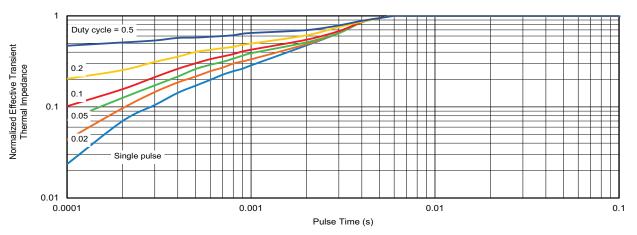


Fig. 12 - Normalized Transient Thermal Impedance, Junction-to-Case

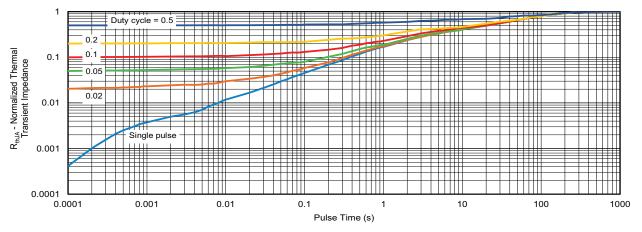


Fig. 13 - Normalized Thermal Transient Impedance, Junction-to-Ambient

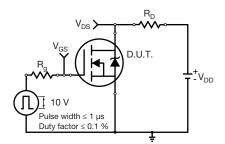


Fig. 14 - Switching Time Test Circuit

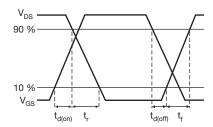


Fig. 15 - Switching Time Waveforms

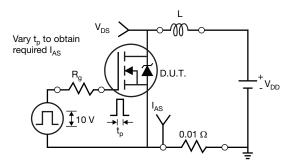


Fig. 16 - Unclamped Inductive Test Circuit

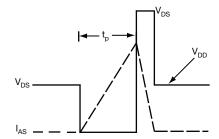


Fig. 17 - Unclamped Inductive Waveforms

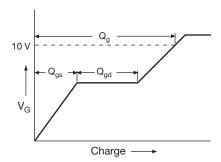


Fig. 18 - Basic Gate Charge Waveform

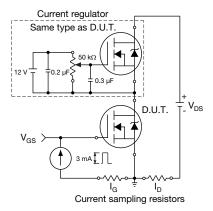
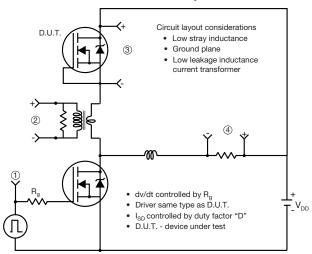


Fig. 19 - Gate Charge Test Circuit



#### Peak Diode Recovery dv/dt Test Circuit



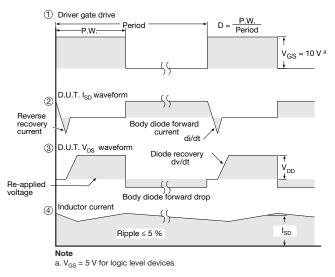


Fig. 20 - For N-Channel

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# PowerPAK® 8 x 8 Case Outline







DIM	MILLIMETERS		INCHES			
DIM.	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.
А	0.95	1.00	1.05	0.037	0.039	0.041
A1	0.00	-	0.05	0.000	-	0.002
A2	020 ref.		0.008 ref.			
b	0.95	1.00	1.05	0.037	0.039	0.041
D	7.90	8.00	8.10	0.311	0.315	0.319
D2	7.10	7.20	7.30	0.280	0.283	0.287
D3	0.40 BSC		0.016 BSC			
е	2.00 BSC		0.079 BSC			
Е	7.90	8.00	8.10	0.311	0.315	0.319
E2	4.30	4.35	4.40	0.169	0.171	0.173
E3	0.40 BSC		0.40 BSC 0.016 BSC			
K	2.75 BSC		0.108 BSC			
L	0.45	0.50	0.55	0.018	0.020	0.022
N <sup>(3)</sup>	8				8	

#### Notes

- (1) Use millimeters as the primary measurement
- (2) Dimensioning and tolerances conform to ASME Y14.5 M 1994
- (3) N is the number of terminals
- (4) The pin 1 identifier must be existed on the top surface of the package by using indentation mark or other feature of package body
- (5) Exact shape and size of this feature is optional

ECN: E20-0518-Rev. B, 28-Sep-2020

DWG: 6041

Revision: 28-Sep-2020 1 Document Number: 67859



# Recommended Minimum PADs for PowerPAK® 8 mm x 8 mm



Dimensions in millimeters



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